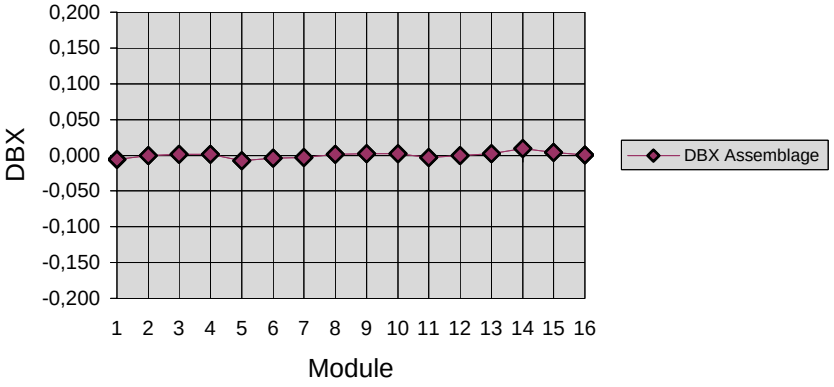
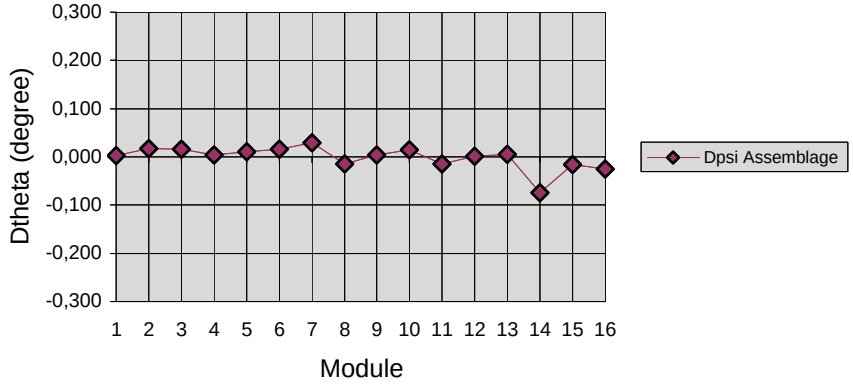
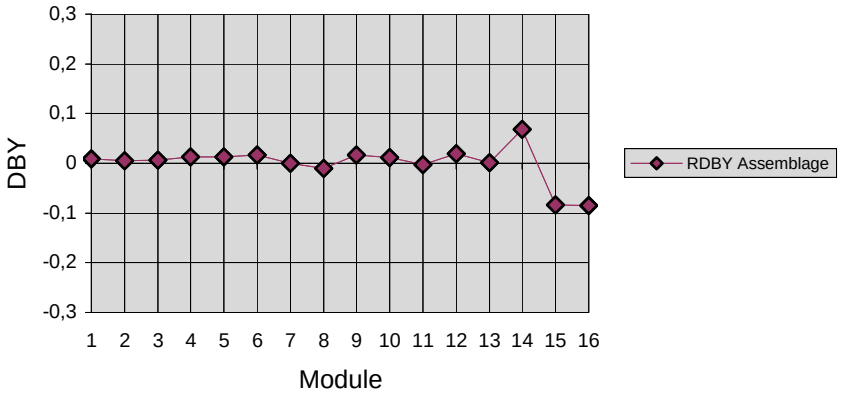
## DBX (large edge)




## Rotation in the wafer plane




## DBY (small edge)




| | | |
|---|---|---|
| Ass. Order | | 20 |
| Lad | | 3 |
| Position | Run IV | XX |
| | Run V | 1 |
| | Run VI | 1 |
| | | |

Ladder not surveyed. Data taken from the ladder assembly operations.
Module 15 shifted by 100 microns in Y
Module 16 shifted by 130 microns in Y